

SOT385-1

plastic leadless module carrier

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	PLLMC
Package type industry code	PLLMC
Package style descriptive code	PLLMC (plastic leadless module carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-9-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	5.9	-	6	6.1	mm
A ₂	package height	2.9	-	3	3.05	mm
n ₂	actual quantity of termination	-	-	0	-	



2. Package outline

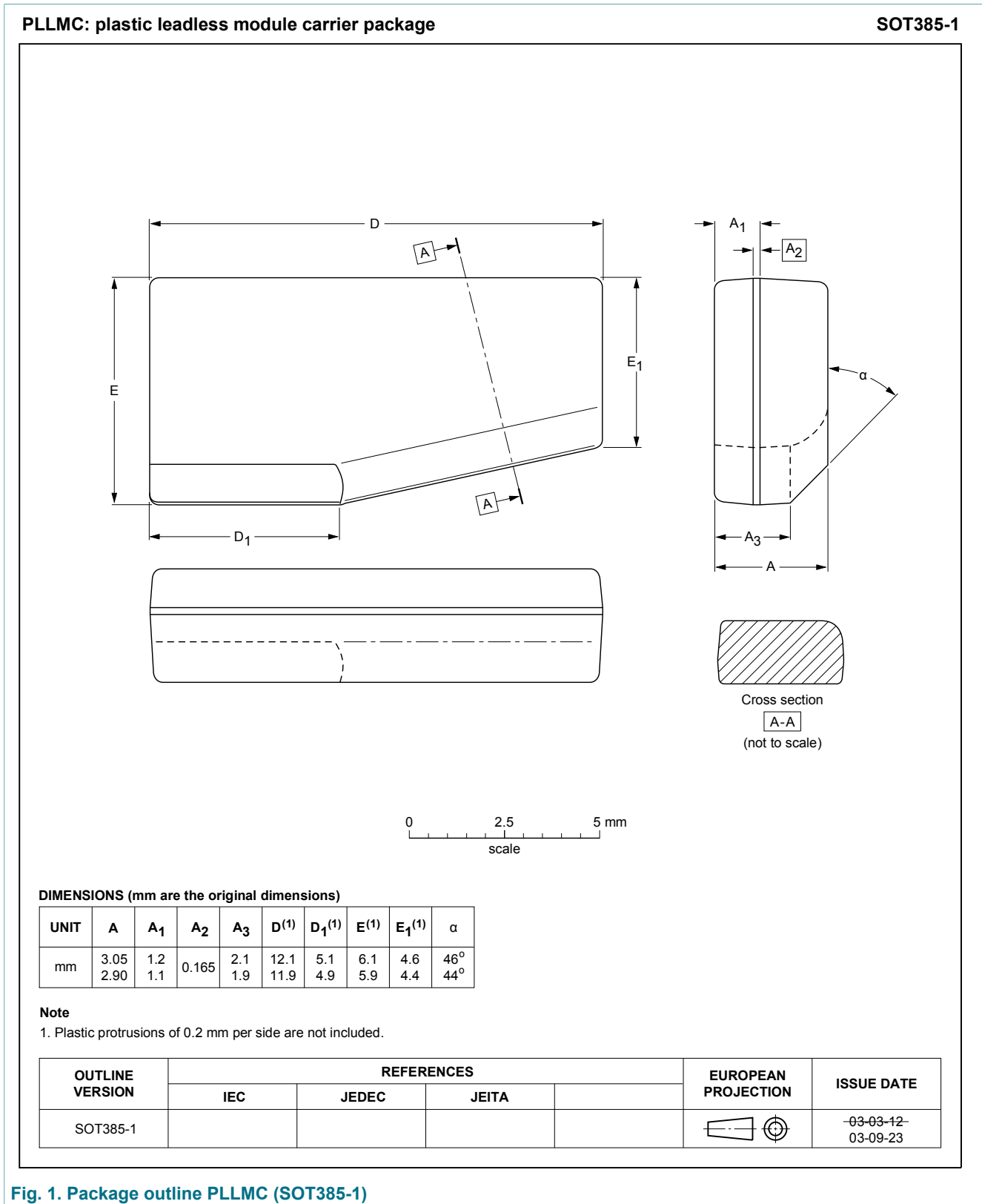


Fig. 1. Package outline PLLMC (SOT385-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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